

AMENDMENT TO THE CLAIMS

1. (ORIGINAL) An optical communication module, comprising:
a substrate;
a transmitter comprising a light-emitter element and a driver IC operative to drive said light-emitter;
a receiver comprising a photodetector element and an amplifier IC operative to amplify an output signal from said photodetector; and
circuit components accompanied with said said transmitter and receiver;
wherein said transmitter, receiver and circuit components are implemented on said substrate, wherein said substrate comprises a ceramic substrate made of laminated green sheets and at least two recesses formed thereon, and said light-emitting element and photodetector element are mounted into said separate recesses and said recesses are separately covered with a mold resin by molding, and wherein depths of said recesses formed are each deeper than a mounted height of said light-emitter or photodetector elements mounted thereinto.

2. (ORIGINAL) The optical communication module according to claim 1, wherein a color of said ceramic substrate is white.

3. (CURRENTLY AMENDED) The optical communication module to claim 1 ~~or 2~~, wherein said recesses include at least a recess exclusive for said light-emitter element and a recess exclusive for said photodetector element, each exclusive recess being formed in a tapered shape with a conical horn within a range of a

depth roughly corresponding to that of the mounted heights of the elements, and said elements mounted in said exclusive recesses being separately covered with a transparent resin.

4. (CURRENTLY AMENDED) The optical communication module according to ~~any one of claim 1 to 3~~, wherein each covering in said recess is molded by means of a potting mold method using a dispenser.

5. (NEW) The optical communication module to claim 2, wherein said recesses include at least a recess exclusive for said light-emitter element and a recess exclusive for said photodetector element, each exclusive recess being formed in a tapered shape with a conical horn within a range of a depth roughly corresponding to that of the mounted heights of the elements, and said elements mounted in said exclusive recesses being separately covered with a transparent resin.

6. (NEW) The optical communication module according to claim 2, wherein each covering in said recess is molded by means of a potting mold method using a dispenser.

7. (NEW) The optical communication module according to claim 3, wherein each covering in said recess is molded by means of a potting mold method using a dispenser.

8. The optical communication module to claim 2, wherein; said recesses include at least a recess exclusive for said light-emitter element and a recess exclusive for said photodetector element, each exclusive recess being formed in a

tapered shape with a conical horn within a range of a depth roughly corresponding to that of the mounted heights of the elements, and said elements mounted in said exclusive recesses being separately covered with a transparent resin;

each covering in said recess is molded by means of a potting mold method using a dispenser.